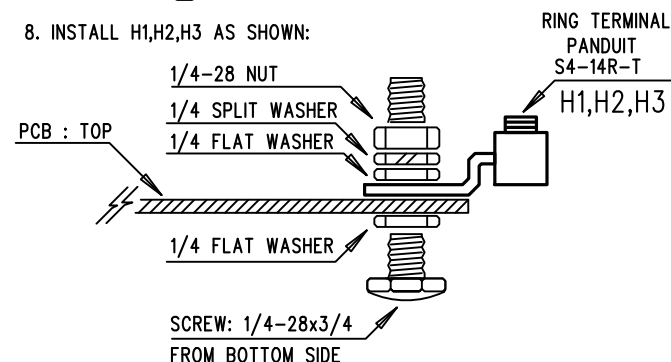




1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL DLED1-DLED8 AS SHOW:



8. INSTALL H1,H2,H3 AS SHOWN:



APPROVALS		 ANALOG DEVICES		 POWER BY LINEAR		1630 McCARTHY BLVD MILPITAS, CA 95035 TEL: (408)432-1900	
PCB DES.	KIM T.	www.analog.com		www.linear.com			
APP ENG.	SAL A.	TITLE: TOP ASSEMBLY DRAWING					
		HIGH POWER NEGATIVE VOLTAGE HOT SWAP CONTROLLER					
		WITH I2C POWER MONITOR AND EEPROM					
		SIZE N/A	IC NO.	LTC4284IUHG DEMO CIRCUIT 2470A		REV. 3	
SCALE = NONE		FILENAME: DC2470A-3.PCB				SHT 1 OF 2	